Vishay Siliconix

P-Channel 20 V (D-S) MOSFET



Marking Code: H2

PRODUCT SUMMARY						
V _{DS} (V)	-20					
$R_{DS(on)}$ max. (Ω) at V_{GS} = -10 V	0.028					
$R_{DS(on)}$ max. (Ω) at $V_{GS} = -4.5$ V	0.037					
$R_{DS(on)}$ max. (Ω) at $V_{GS} = -2.5$ V	0.0556					
Q _g typ. (nC)	7.0					
I _D (A) ^a	-6.5					
Configuration	Single					

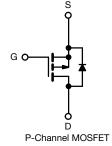
FEATURES

- TrenchFET® gen V p-channel MOSFET
- 100 % R_g and UIS tested
- Material categorization: for definitions of compliance please see www.vishay.com/doc?99912



APPLICATIONS

- · Load switches
- DC/DC converters
- Power management
- LED backlighting



ORDERING INFORMATION	
Package	SOT-23 (TO-236)
Lead (Pb)-free and halogen-free	Si2399BDS-T1-GE3

PARAMETER		SYMBOL	LIMIT	UNIT	
Drain-source voltage		V _{DS}	-20		
Gate-source voltage		V _{GS}	± 12	V	
Continuous drain current (T _J = 150 °C) ^a	T _F = 25 °C		-6.5		
	T _F = 70 °C	1 . [-5.2		
	T _A = 25 °C	I _D	-5.4 b, c	A	
	T _A = 70 °C		-4.2 ^{b, c}		
Pulsed drain current (V _{GS} = 10 V, t = 100 μs)	I _{DM}	-30	7		
Continuous source-drain diode current	T _F = 25 °C	,	-1.6	^	
	T _A = 25 °C	- I _S	-1.1 ^{b, c}	A	
Maximum power dissipation ^a	T _F = 25 °C		1.8		
	T _F = 70 °C	1 5	1.14	10/	
	T _A = 25 °C	P _D	1.25 ^{b, c}	W	
	T _A = 70 °C		0.8 b, c		
Operating junction and storage temperature rar	T _J , T _{stq}	-55 to +150	°C		

THERMAL RESISTANCE RATINGS						
PARAMETER		SYMBOL	TYPICAL	MAXIMUM	UNIT	
Maximum junction-to-ambient b, d	t ≤ 5 s	R_{thJA}	80	100	°C/W	
Maximum junction-to-foot (drain)	Steady state	R_{thJF}	55	70	C/ VV	

Notes

- a. $T_F = 25$ °C
- b. Surface mounted on 1" x 1" FR4 board
- c. t = 5 s
- d. Maximum under steady state conditions is 130 $^{\circ}\text{C/W}$



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PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNIT	
Static			L				
Drain-source breakdown voltage	V _{DS}	$V_{GS} = 0 \text{ V}, I_D = -250 \mu\text{A}$	-20	-	-	V	
V _{DS} temperature coefficient	$\Delta V_{DS}/T_{J}$	I _D = -10 mA	-	-14.2	-	\//00	
V _{GS(th)} temperature coefficient	$\Delta V_{GS(th)}/T_J$	I _D = -250 μA	-	3.2	-	mV/°C	
Gate-source threshold voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_D = -250 \mu A$	-0.6	-	-1.5	V	
Gate-source leakage	I _{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 12 \text{ V}$	-	-	± 100	nA	
		V _{DS} = -20 V, V _{GS} = 0 V	-	-	-1	μА	
Zero gate voltage drain current	I _{DSS}	V _{DS} = -20 V, V _{GS} = 0 V, T _J = 55 °C	-	-	-10		
		$V_{GS} = -10 \text{ V}, I_D = -5 \text{ A}$	-	0.022	0.028		
Drain-source on-state resistance ^a	R _{DS(on)}	V _{GS} = -4.5 V, I _D = -3 A	-	0.027	0.037	Ω	
		V _{GS} = -2.5 V, I _D = -2 A	-	0.038	0.0556		
Forward transconductance	9 _{fs}	V _{DS} = -10 V, I _D = -6 A	-	20	-	S	
Dynamic ^b			L				
Input capacitance	C _{iss}		-	730	-	pF	
Output capacitance	C _{oss}	V _{DS} = -10 V, V _{GS} = 0 V, f = 1 MHz	-	125	-		
Reverse transfer capacitance	C _{rss}		-	100	-		
Total gate charge	Q_g	V _{DS} = -10 V, V _{GS} = 10 V, I _D = -10 A	-	15	5 23		
			-	7	11	nC	
Gate-source charge	Q_{gs}	$V_{DS} = -10 \text{ V}, V_{GS} = 4.5 \text{ V}, I_{D} = 10 \text{ A}$	-	1.8	-		
Gate-drain charge	Q _{gd}		-	1.8	-		
Gate resistance	Rq	f = 1 MHz	1.3	6.5	13	Ω	
Turn-on delay time	t _{d(on)}		-	12	25		
Rise time	t _r	$V_{DD} = -10 \text{ V, R}_{L} = 1 \Omega$	-	32	65	ns	
Turn-off delay time	t _{d(off)}	$I_D \cong -10 \text{ A}, V_{GEN} = -4.5 \text{ V}, R_g = 1 \Omega$	-	22	45		
Fall time	t _f		-	10	20		
Turn-on delay time	t _{d(on)}		-	7	15		
Rise time	t _r	$V_{DD} = -10 \text{ V, R}_{L} = 1 \Omega$	-	5	10		
Turn-off delay time	t _{d(off)}	$I_D \cong -10 \text{ A}, V_{GEN} = -10 \text{ V}, R_g = 1 \Omega$	-	19	40	ns	
Fall time	t _f		-	7	15		
Drain-Source Body Diode Characterist	ics						
Continous source-drain diode current	I _S	T _C = 25 °C	-	-	-1.6	^	
Pulse diode forward current ^a	I _{SM}		-	-	-30	Α	
Body diode voltage	V _{SD}	$I_S = -5 \text{ A}, V_{GS} = 0 \text{ V}$	-	-0.83	-1.1	V	
Body diode reverse recovery charge	Q _{rr}		-	2.5	5	nC	
Body diode reverse recovery time	t _{rr}	I _F = -10 A, dl/dt = 100 A/μs,	-	8	20		
Reverse recovery fall time	t _a	T _J = 25 °C	-	5	-	ns	
Reverse recovery rise time	t _b		-	3	-		

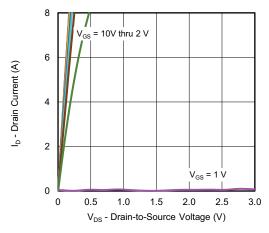
Notes

- a. Pulse test; pulse width $\leq 300~\mu s,$ duty cycle $\leq 2~\%$
- b. Guaranteed by design, not subject to production testing

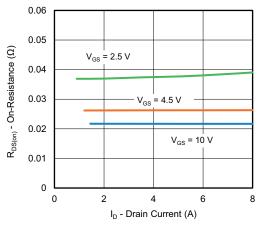
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.



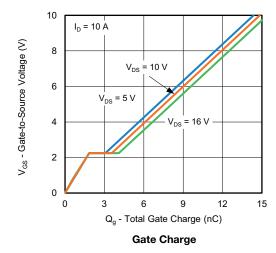
TYPICAL CHARACTERISTICS (T_A= 25 °C, unless otherwise noted)

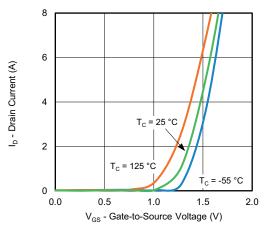


Output Characteristics

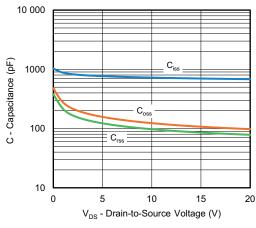


On-Resistance vs. Drain Current

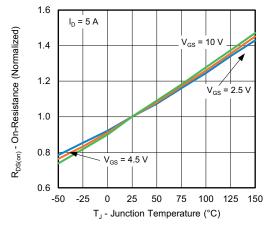




Transfer Characteristics Curves vs. Temperature



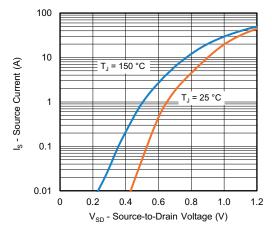
Capacitance



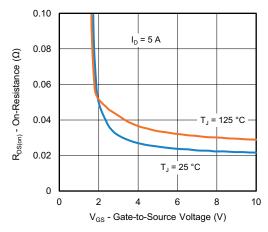
On-Resistance vs. Junction Temperature



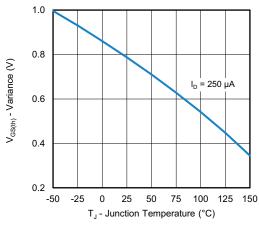
TYPICAL CHARACTERISTICS (T_A= 25 °C, unless otherwise noted)



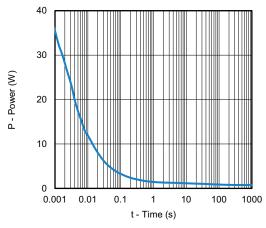
Source-Drain Diode Forward Voltage



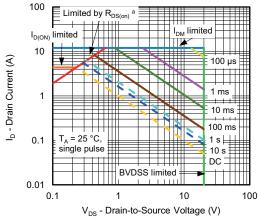
R_{DS(on)} vs. V_{GS} vs. Temperature



Threshold Voltage



Single Pulse Power



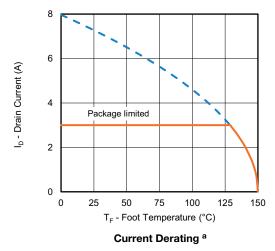
Safe Operating Area, Junction-to-Ambient

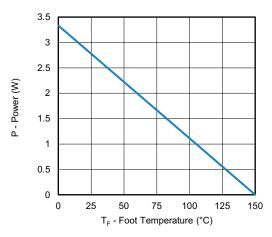
Note

a. V_{GS} > minimum V_{GS} at which R_{DS(on)} is specified



TYPICAL CHARACTERISTICS (T_A = 25°C, unless otherwise noted)





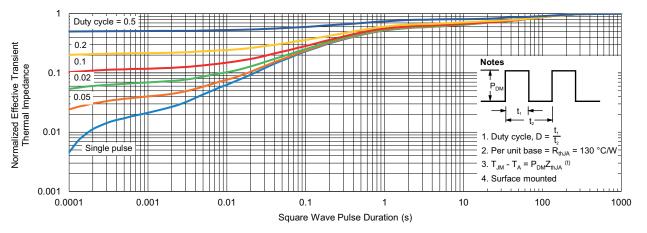
Power, Junction-to-Foot

Note

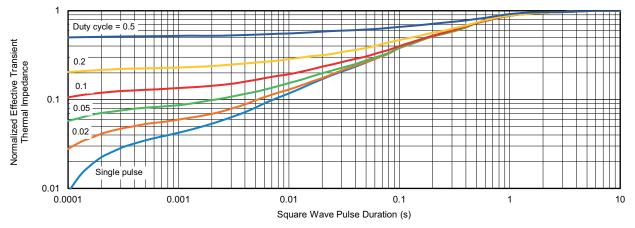
a. The power dissipation P_D is based on T_J max. = 150 °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit



TYPICAL CHARACTERISTICS (T_A = 25 °C, unless otherwise noted)



Normalized Thermal Transient Impedance, Junction-to-Ambient



Normalized Thermal Transient Impedance, Junction-to-Foot

Vishay Siliconix maintains worldwide manufacturing capability. Products may be manufactured at one of several qualified locations. Reliability data for Silicon Technology and Package Reliability represent a composite of all qualified locations. For related documents such as package / tape drawings, part marking, and reliability data, see www.vishay.com/ppg?61604.

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SOT-23 (TO-236): 3-LEAD







Dim	MILLI	METERS	INCHES		
	Min	Max	Min	Max	
Α	0.89	1.12	0.035	0.044	
A ₁	0.01	0.10	0.0004	0.004	
A ₂	0.88	1.02	0.0346	0.040	
b	0.35	0.50	0.014	0.020	
С	0.085	0.18	0.003	0.007	
D	2.80	3.04	0.110	0.120	
E	2.10	2.64	0.083	0.104	
E ₁	1.20	1.40	0.047	0.055	
е	0.95 BSC		0.0374 Ref		
e ₁	1.90 BSC		0.0748 Ref		
L	0.40	0.60	0.016	0.024	
L ₁	0.64 Ref		0.025 Ref		
S	0.50 Ref		0.020 Ref		
q	3°	8°	3°	8°	
FCN: S-03946-Rev K 09-	lul-01	•			

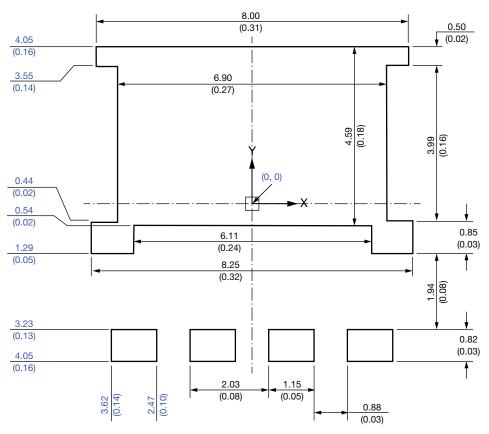
ECN: S-03946-Rev. K, 09-Jul-01

DWG: 5479

Document Number: 71196 www.vishay.com 09-Jul-01



Recommended Minimum PADs for PowerPAK® 8 x 8L Single



Dimensions in millimeters (inches)

Note

• Linear dimensions are in black, the same information is provided in ordinate dimensions which are in blue.



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